

PATENT ASSIGNMENT

Electronic Version v1.1
 Stylesheet Version v1.1

SUBMISSION TYPE:	NEW ASSIGNMENT												
NATURE OF CONVEYANCE:	ASSIGNMENT												
CONVEYING PARTY DATA													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:70%;">Name</th> <th>Execution Date</th> </tr> </thead> <tbody> <tr> <td>Ming-Chang Hsieh</td> <td>06/30/2008</td> </tr> <tr> <td>Hung-Lin Chen</td> <td>06/30/2008</td> </tr> <tr> <td>Hsiu-Mei Yu</td> <td>07/01/2008</td> </tr> <tr> <td>Chin Kun Lan</td> <td>07/01/2008</td> </tr> <tr> <td>Dong-Lung Lee</td> <td>07/01/2008</td> </tr> </tbody> </table>		Name	Execution Date	Ming-Chang Hsieh	06/30/2008	Hung-Lin Chen	06/30/2008	Hsiu-Mei Yu	07/01/2008	Chin Kun Lan	07/01/2008	Dong-Lung Lee	07/01/2008
Name	Execution Date												
Ming-Chang Hsieh	06/30/2008												
Hung-Lin Chen	06/30/2008												
Hsiu-Mei Yu	07/01/2008												
Chin Kun Lan	07/01/2008												
Dong-Lung Lee	07/01/2008												
RECEIVING PARTY DATA													
Name:	Taiwan Semiconductor Manufacturing Company, Ltd.												
Street Address:	No. 8, Li-Hsin Rd. 6												
Internal Address:	Science-Based Industrial Park												
City:	Hsin-Chu												
State/Country:	TAIWAN												
Postal Code:	300-77												
PROPERTY NUMBERS Total: 1													
<table border="1" style="width:100%; border-collapse: collapse;"> <thead> <tr> <th style="width:30%;">Property Type</th> <th>Number</th> </tr> </thead> <tbody> <tr> <td>Application Number:</td> <td>13164523</td> </tr> </tbody> </table>		Property Type	Number	Application Number:	13164523								
Property Type	Number												
Application Number:	13164523												
CORRESPONDENCE DATA													
Fax Number:	(214)200-0853												
<i>Correspondence will be sent via US Mail when the fax attempt is unsuccessful.</i>													
Phone:	214-651-5000												
Email:	ipdocketing@haynesboone.com												
Correspondent Name:	Haynes and Boone LLP												
Address Line 1:	2323 Victory Avenue												
Address Line 2:	Suite 700												
Address Line 4:	Dallas, TEXAS 75219												
ATTORNEY DOCKET NUMBER:	2008-0033-D/24061.1845												

OP \$40.00 13164523

501571000

**PATENT
 REEL: 026470 FRAME: 0111**

NAME OF SUBMITTER:

David M. O'Dell

Total Attachments: 3

source=1845Assignment#page1.tif

source=1845Assignment#page2.tif

source=1845Assignment#page3.tif

ASSIGNMENT

WHEREAS, we,

- | | | | |
|-----|------------------|----|--|
| (1) | Ming-Chang Hsieh | of | 9F, No. 390, Sec. 3, Jhongsing Road, Jhudong Township
Hsinchu County 310, Taiwan, R.O.C. |
| (2) | Hung-Lin Chen | of | No. 18, Alley 35, Lane 405, Jianguo Road
Pingtung City, Pingtung County 900, Taiwan, R.O.C. |
| (3) | Hsiu-Mei Yu | of | No. 30, Lane 239, Ming-Shing Road, Judung Jen
Hsinchu 310, Taiwan, R.O.C. |
| (4) | Chin Kun Lan | of | 9F, No. 29, Lane 62, Hsin Yuan Street
Hsin-Chu City, Taiwan, R.O.C. |
| (5) | Dong-Lung Lee | of | No. 24, Chaoliang Street
Kaohsiung City, Taiwan, R.O.C. |

have invented certain improvements in

DIFFUSION REGION ROUTING FOR NARROW SCRIBE-LINE DEVICES

for which we have executed an application for Letters Patent of the United States of America,

 of even date filed herewith; and
 X filed on July 15, 2008 and assigned application number 12/173,121; and

WHEREAS, we authorize the attorney of record to update this document to include Patent Office information as deemed necessary (i.e., filing date, serial number, etc.);

WHEREAS, Taiwan Semiconductor Manufacturing Company, Ltd., ("TSMC"), No. 8, Li-Hsin Rd. 6, Science-Based Industrial Park, Hsin-Chu, Taiwan 300-77, R.O.C. is desirous of obtaining the entire right, title, and interest in, to and under the said invention and the said application in the United States of America and in any and all countries foreign thereto;

NOW, THEREFORE, for One Dollar (\$1.00) and other good and valuable consideration, the receipt and sufficiency of which is hereby acknowledged, and other good and valuable consideration, we have sold, assigned, transferred and set over, and by these presents do hereby sell, assign, transfer and set over, unto the said TSMC, its successors, legal representatives, and assigns, the entire right, title, and interest in, to and under the said invention, and the said application, and all divisional, renewal, substitutional, and continuing applications thereof, and all Letters Patent of the United States of America which may be granted thereon and all reissues and extensions thereof, and all applications for Letters Patent which may be filed for said invention in any country or countries foreign to the United States of America, and all extensions, renewals, and reissues thereof, and all prior patents and patent applications from which a filing priority of the above-described patent application may be obtained, including the right to collect past damages; and we hereby authorize and request the Commissioner of Patents of the United States of America, and any official of any country or countries foreign to the United States of America,

whose duty it is to issue patents on applications as aforesaid, to issue all Letters Patent for said invention to the said TSMC, its successors, legal representatives and assigns, in accordance with the terms of this instrument.

AND WE HEREBY covenant that we have full right to convey the entire interest herein assigned, and that we have not executed, and will not execute, any agreement in conflict herewith.

AND WE HEREBY further covenant and agree that we will communicate to said TSMC, its successors, legal representatives and assigns, any facts known to us respecting said invention, and testify in any legal proceedings, sign all lawful papers, execute all divisional, renewal, substitutional, continuing, and reissue applications, make all rightful declarations and/or oaths and generally do everything possible to aid the said TSMC, its successors, legal representatives and assigns, to obtain and enforce proper patent protection for said invention in all countries.

Inventor Name: Ming-Chang Hsieh

Residence Address: 9F, No. 390, Sec. 3, Jhongsing Road, Jhudong Township
Hsinchu County 310, Taiwan, R.O.C.

Dated: 2008/06/30

Ming-Chang Hsieh
Inventor Signature

Inventor Name: Hung-Lin Chen

Residence Address: No. 18, Alley 35, Lane 405, Jianguo Road
Pingtung City, Pingtung County 900, Taiwan, R.O.C.

Dated: 2008/06/30

Hung-Lin Chen
Inventor Signature

Inventor Name: Hsiu-Mei Yu
Residence Address: No. 30, Lane 239, Ming-Shing Road, Judung Jen
Hsinchu 310, Taiwan, R.O.C.

Dated: 2008/7/1 Hsiu-Mei Yu
Inventor Signature

Inventor Name: Chin Kun Lan
Residence Address: 9F, No. 29, Lane 62, Hsin Yuan Street
Hsin Chu City, Taiwan, R.O.C.

Dated: 2008/7/1 Chin-Kun Lan
Inventor Signature

Inventor Name: Dong-Lung Lee
Residence Address: No. 24, Chaoliang Street
Kaohsiung City, Taiwan, R.O.C.

Dated: 2008/7/1 Dong-Lung Lee
Inventor Signature
